¨Yب / Descriptions

N ڛ TO-3PH Ł ٦

N-Channel MOSFET in a TO-3PH Plastic Package.

◕ È / Features

ﻫ ĤRDS(ON) Qg Ĥ Ł ɔ

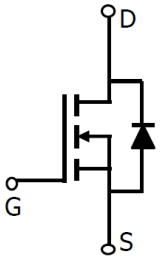
Fast Intrinsic Rectifier,Low $R_{DS(ON)}$ and Q_g,Low Package Inductance

٧ ڀ / Applications

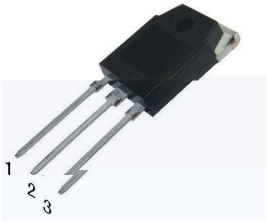
ɔ ز ɔ GF0GF ɨ ´ ɔ ɨ

Switch-Mode and Resonant-Mode Power Supplies,DC-DC Converters,Laser Drivers,AC and DC Motor Drives,Robotics and Servo Controls.

Л ف ق ء ص / Equivalent Circuit



ã ﺍ ؋ / Pinning



PIN1 Gate PIN 2 Drain PIN 3 Source

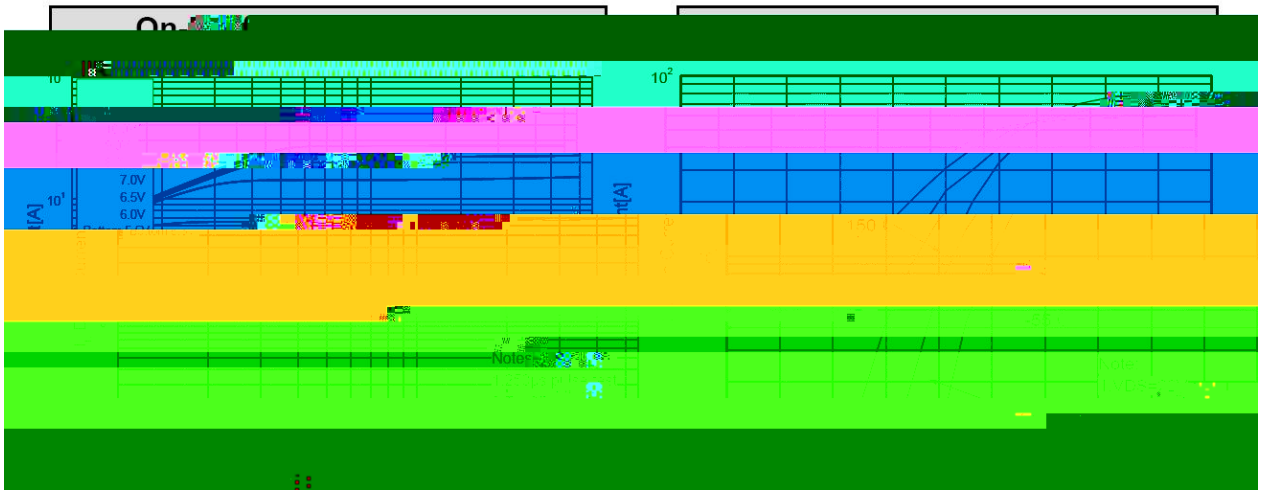
ق ڑ z ł ʜ ɔ̇ / h_{FE} Classifications & Marking

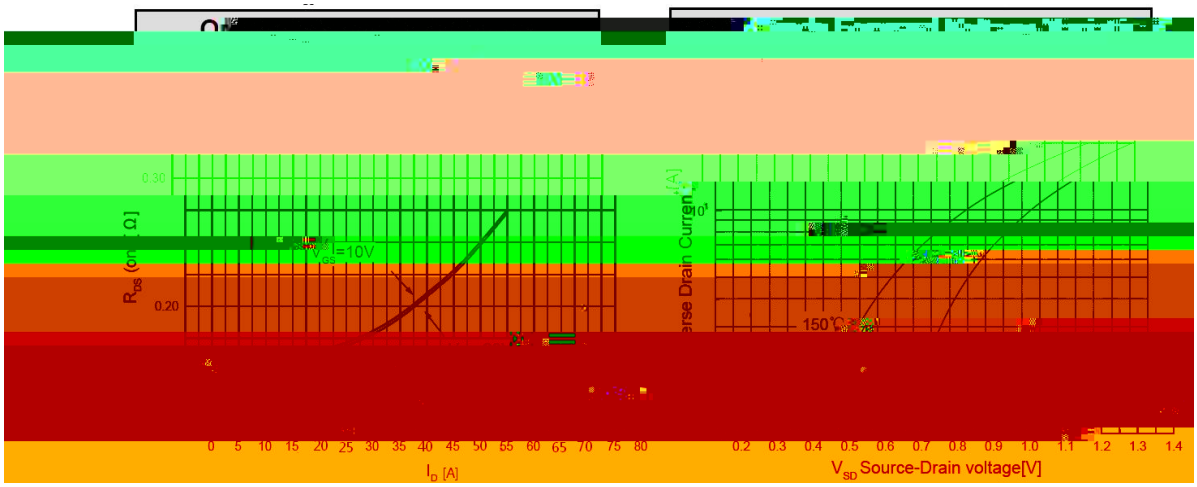
ծ ٦ب See Marking Instructions.

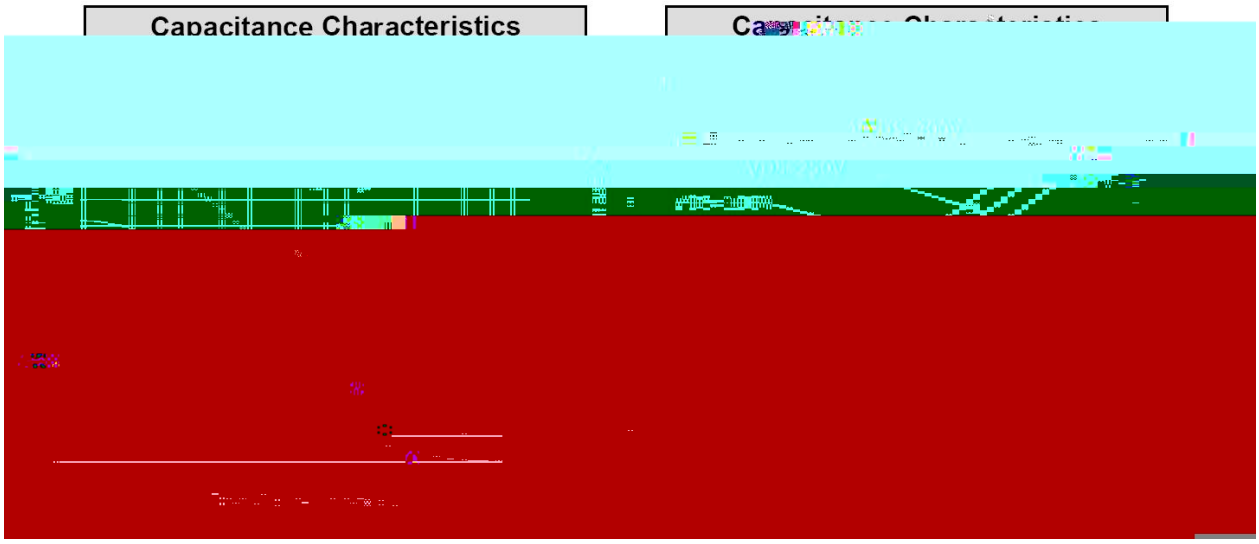
Parameter	Symbol	Rating	Unit
Drain Source Voltage	V_{DSS}	500	V
Gate-Source Voltage	V_{GSS}	±30	V
Drain Continuous- Current(Note 1)	I_D(Tc=25)	26	A

Parameter	Symbol	Test Conditions		Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V	I_D=250μA	500			V
Drain-Source Leakage Current	I_{DSS}	V_{DS}=500V	V_{GS}=0V			1	

≠ ∃ ̃Ą ́E ∨ ∫ / Electrical Characteristic Curve



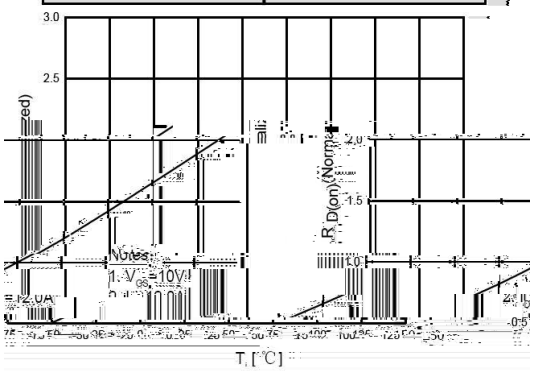




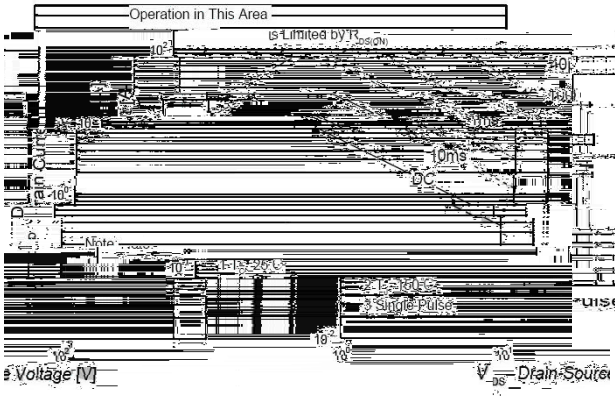
≠ ∧ ∃ Ạ / Electrical Characteristics(Ta=25 ⅃)

Breakdown Voltage Variation

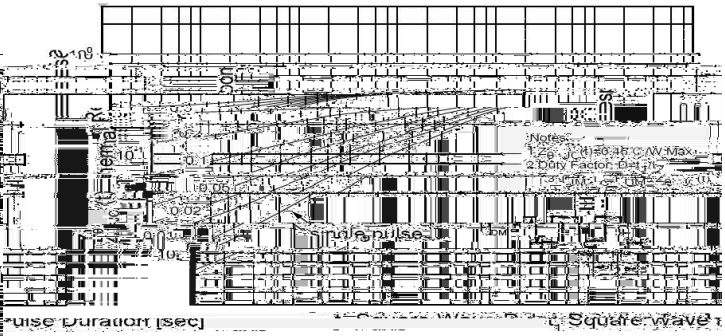
On-Resistance Variation vs. Temperature



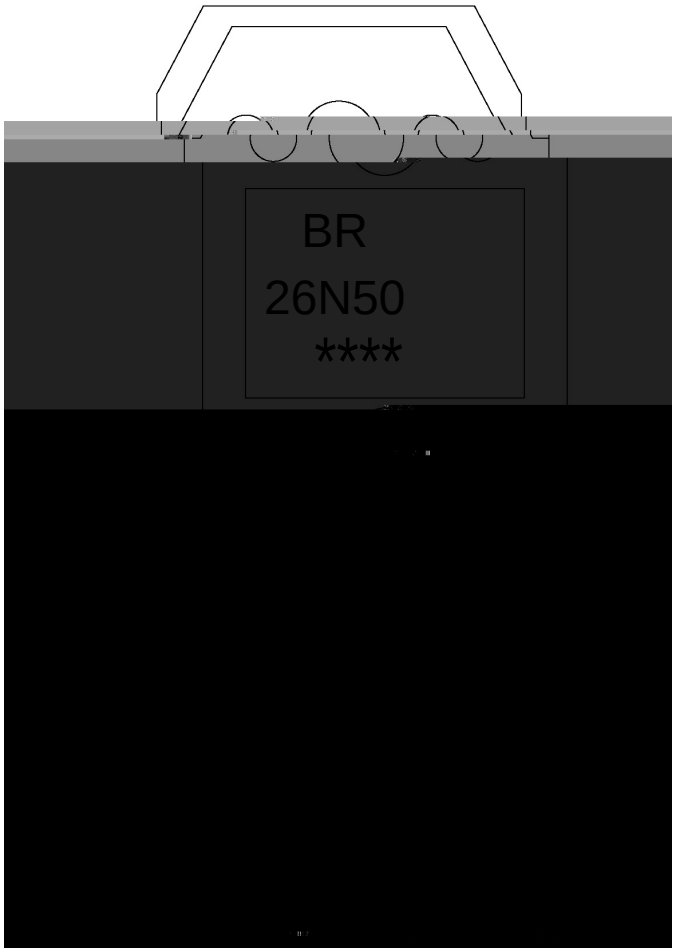
Maximum Safe Operating Area



Transient Thermal Response Curve



ł. ը ̈Ը / Marking Instructions



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BR: И .

26N50 N .

**** N . ₴ N

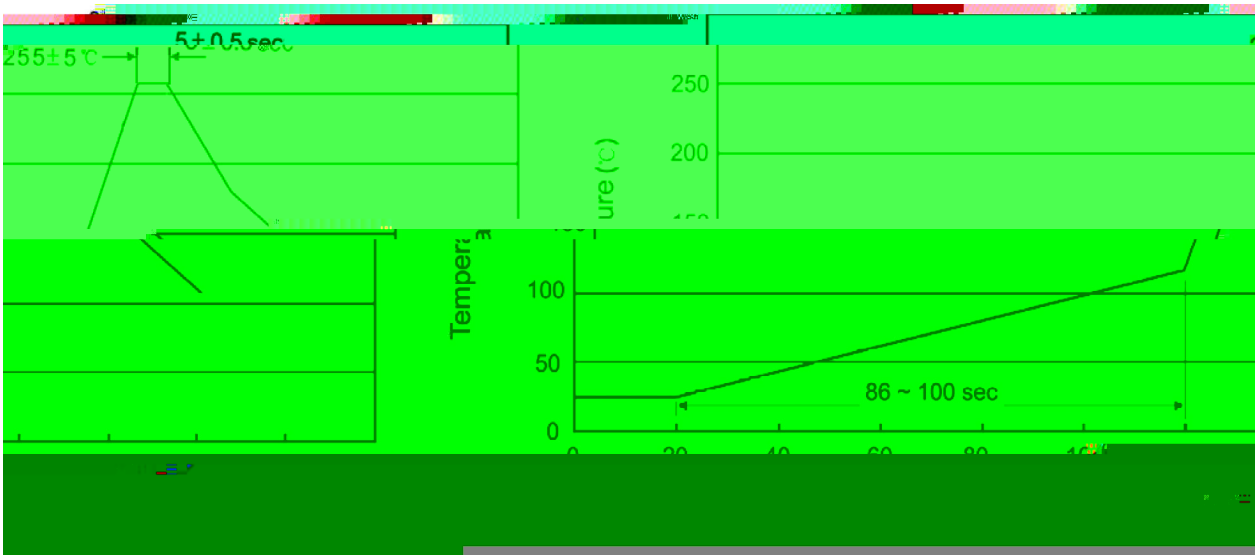
Note:

BR: Company Code.

26N50: Product Type.

****: Lot No. Code, code change with Lot No.

↓ ș ╕ẘ´E ٧ ƒ (ѽ ʊ) / Temperature Profile for Dip Soldering(Pb-Free)



ب

1 Ĺ 25 150 ژ 60 90sec;

2 255±5 ژ ٨ 5±0.5sec;

3 ٧ ھ 2 10 /sec.

Note:

1.Preheating:25~150 , Time:60~90sec.

2.Peak Temp.:255±5 , Duration:5±0.5sec.

3. Cooling Speed: 2~10 /sec.

٧ ü ˆ ˌ ˋ Y Ţ / Resistance to Soldering Heat Test Conditions

270±5 ژ 10±1 sec. Temp:270±5 Time:10±1 sec

ɒ Ч L — / Packaging SPEC.

٦ Ł / TUBE

Package Type	Units					Dimension		(unit mm^3)
	Units/Tube /	Tubes/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Tube	Inner Box	Outer Box
TO-3PH	30	15	450	5	2250	497.5×46×8	555×164×50	575 290 180

ä ٧ ɲ Ѽ / Notices